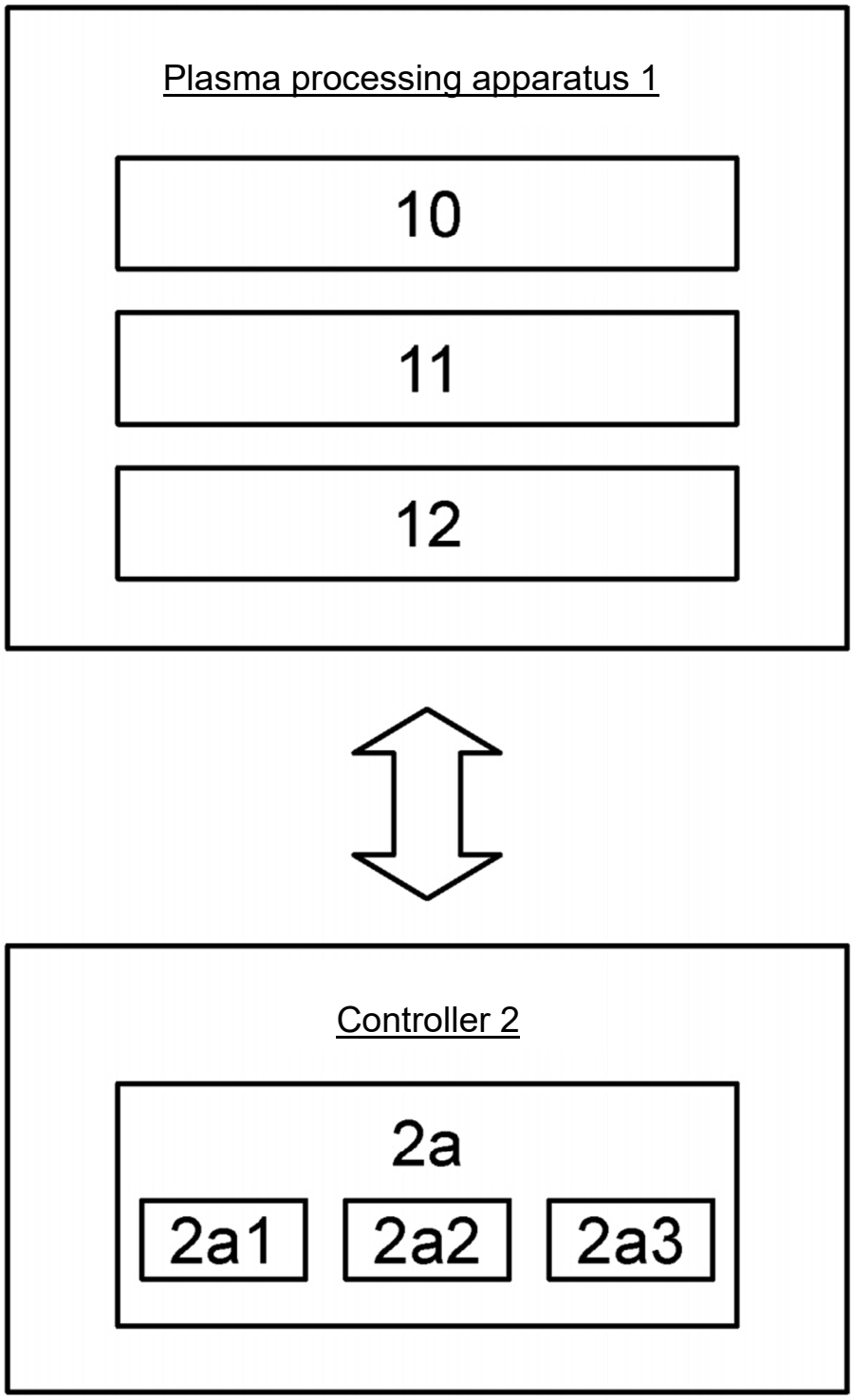
FIG. 1


Plasma processing apparatus 1
10
11
12
Controller 2
2a
2a1
2a2
2a3

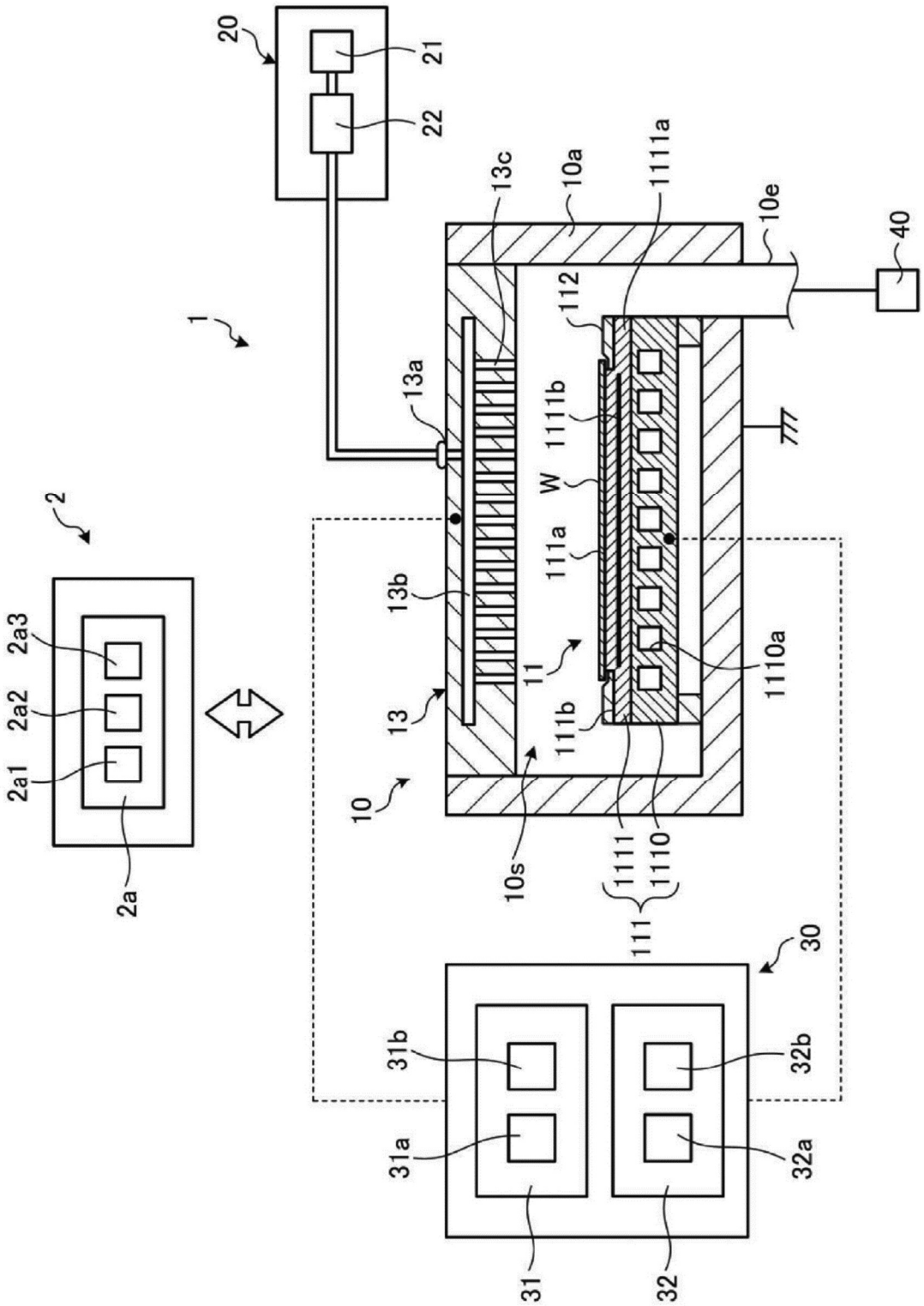

20
21
22
1
13c
10a
1111a
10e
40
112
13a
1111b
W
111a
13b
13
11
111b
1110a
10
10s
1111
1110
111
2
2a3
2a2
2a1
2a
30
31b
32b
31a
32a
31
32

FIG. 2

FIG. 3

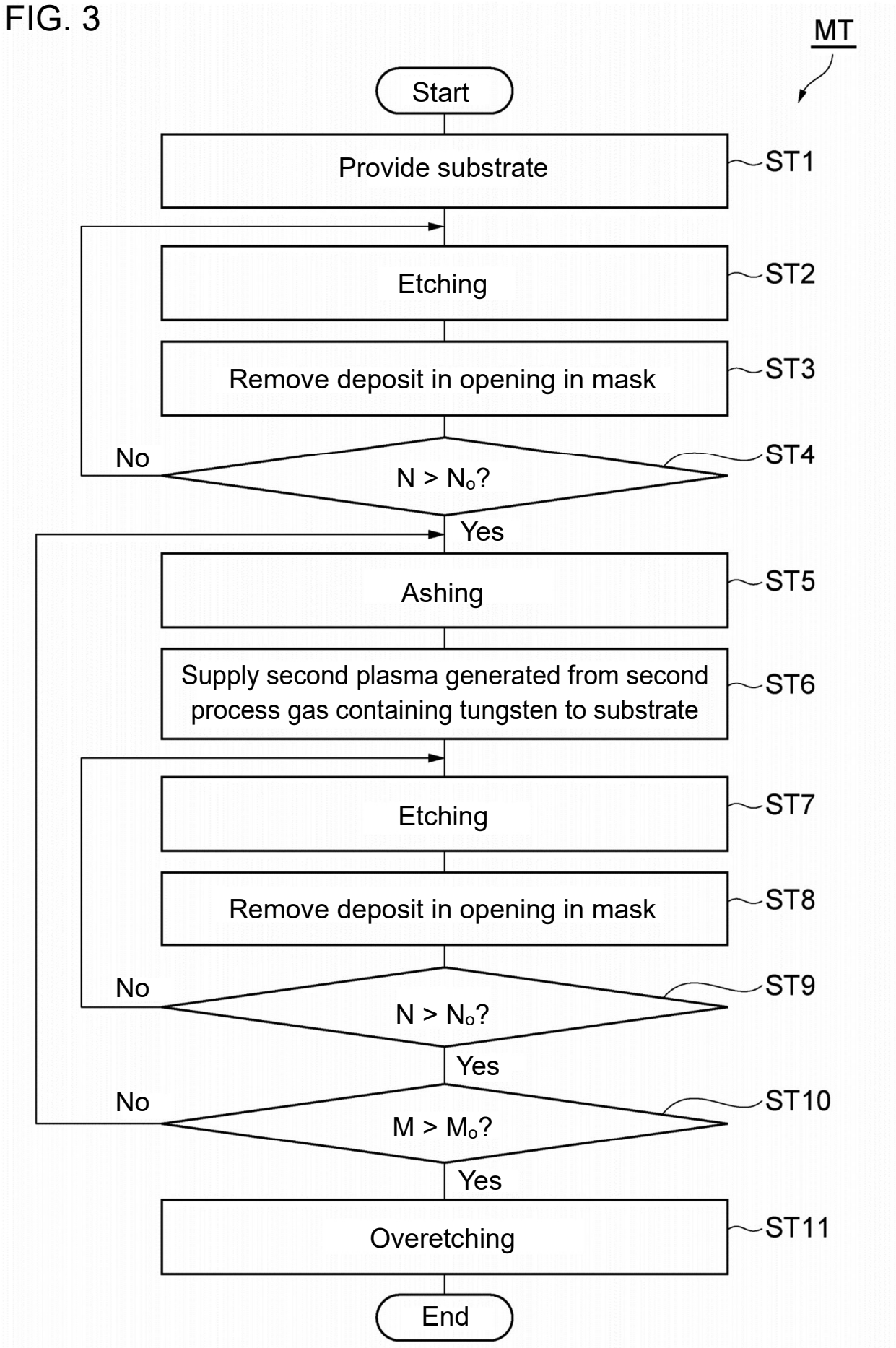

MT
Start
Provide substrate
ST1
Etching
ST2
Remove deposit in opening in mask
ST3
No
N > N₀?
ST4
Yes
Ashing
ST5
Supply second plasma generated from second process gas containing tungsten to substrate
ST6
Etching
ST7
Remove deposit in opening in mask
ST8
No
N > N₀?
ST9
Yes
No
M > M₀?
ST10
Yes
Overetching
ST11
End

FIG. 4

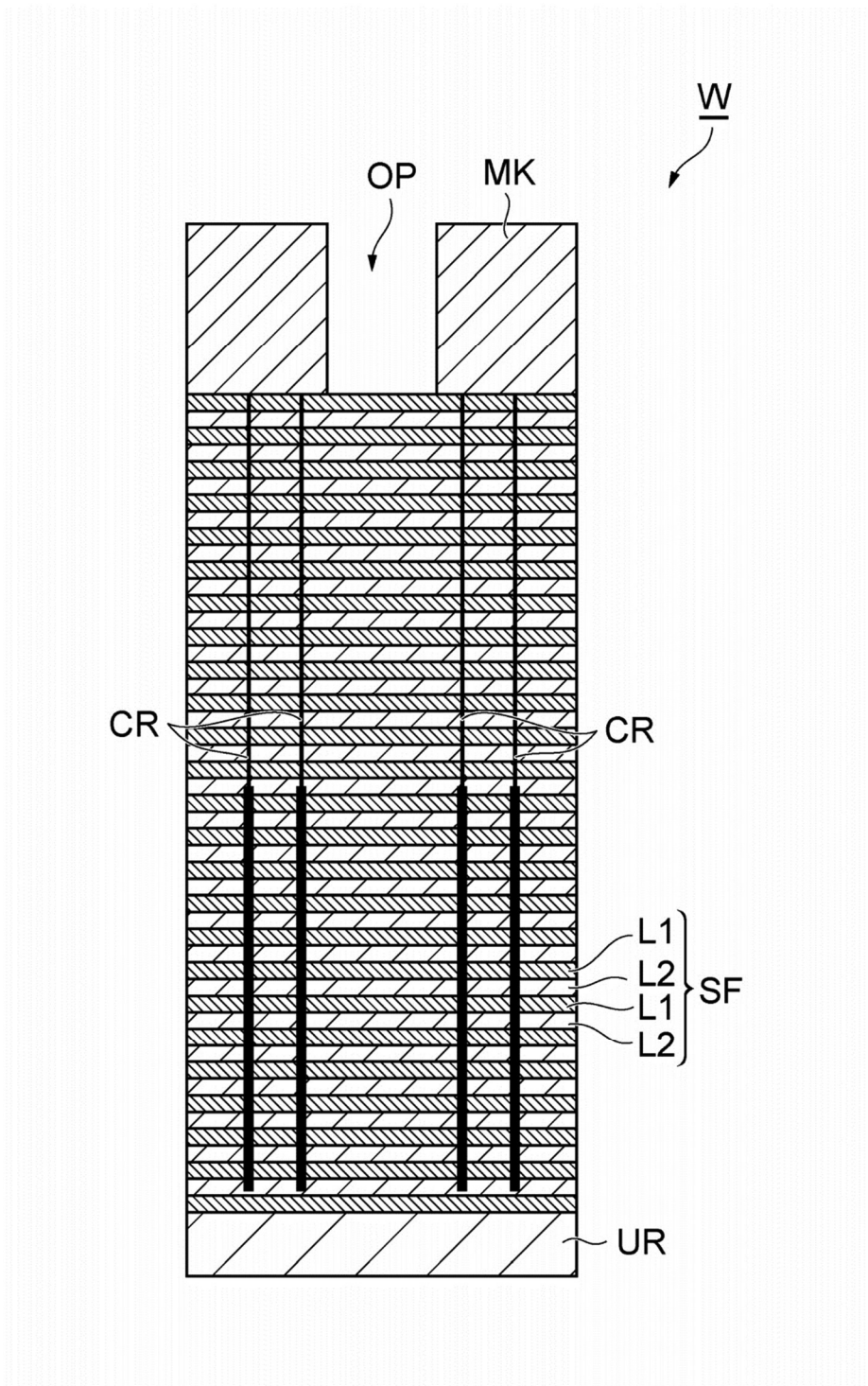


FIG. 5

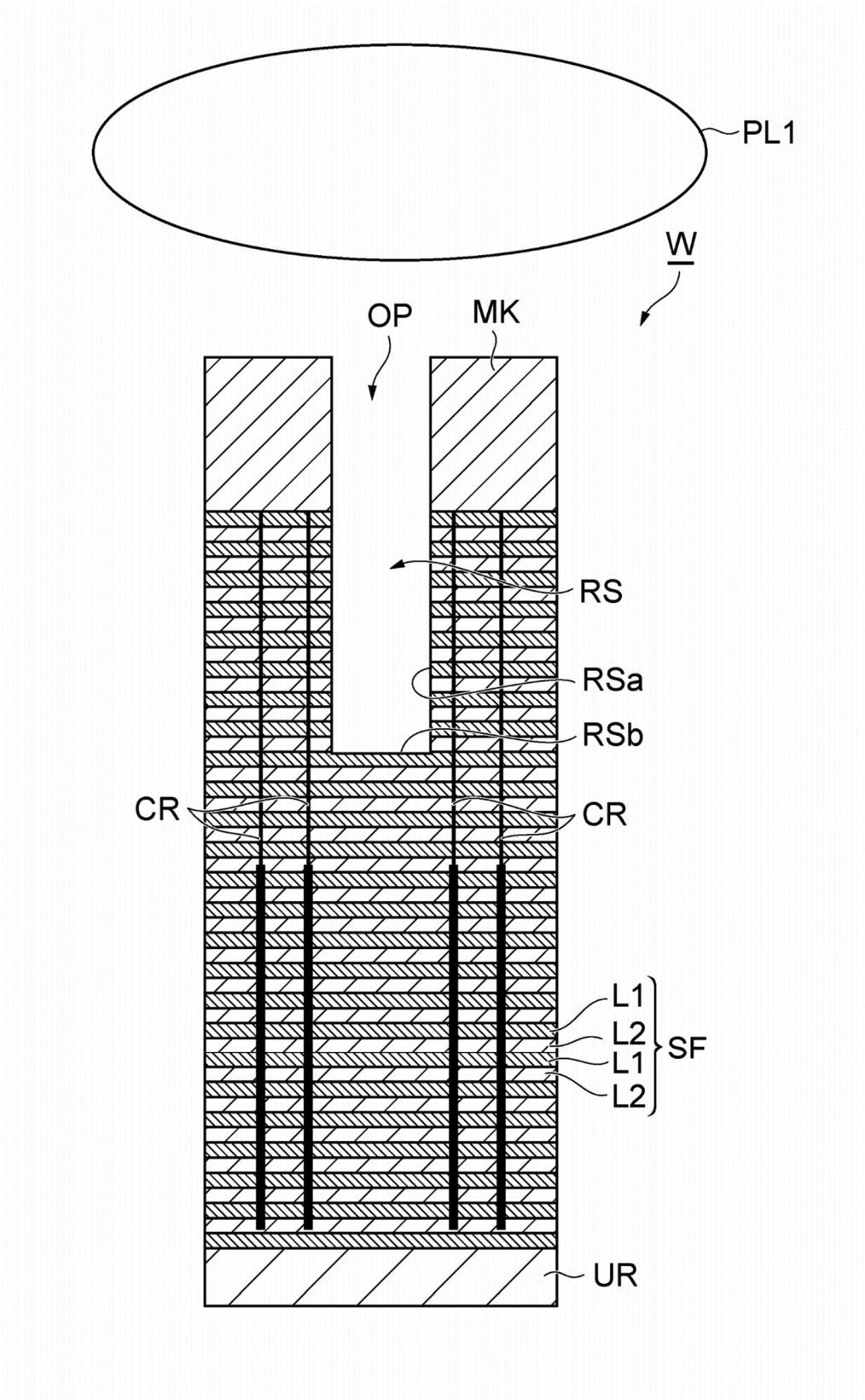


FIG. 6

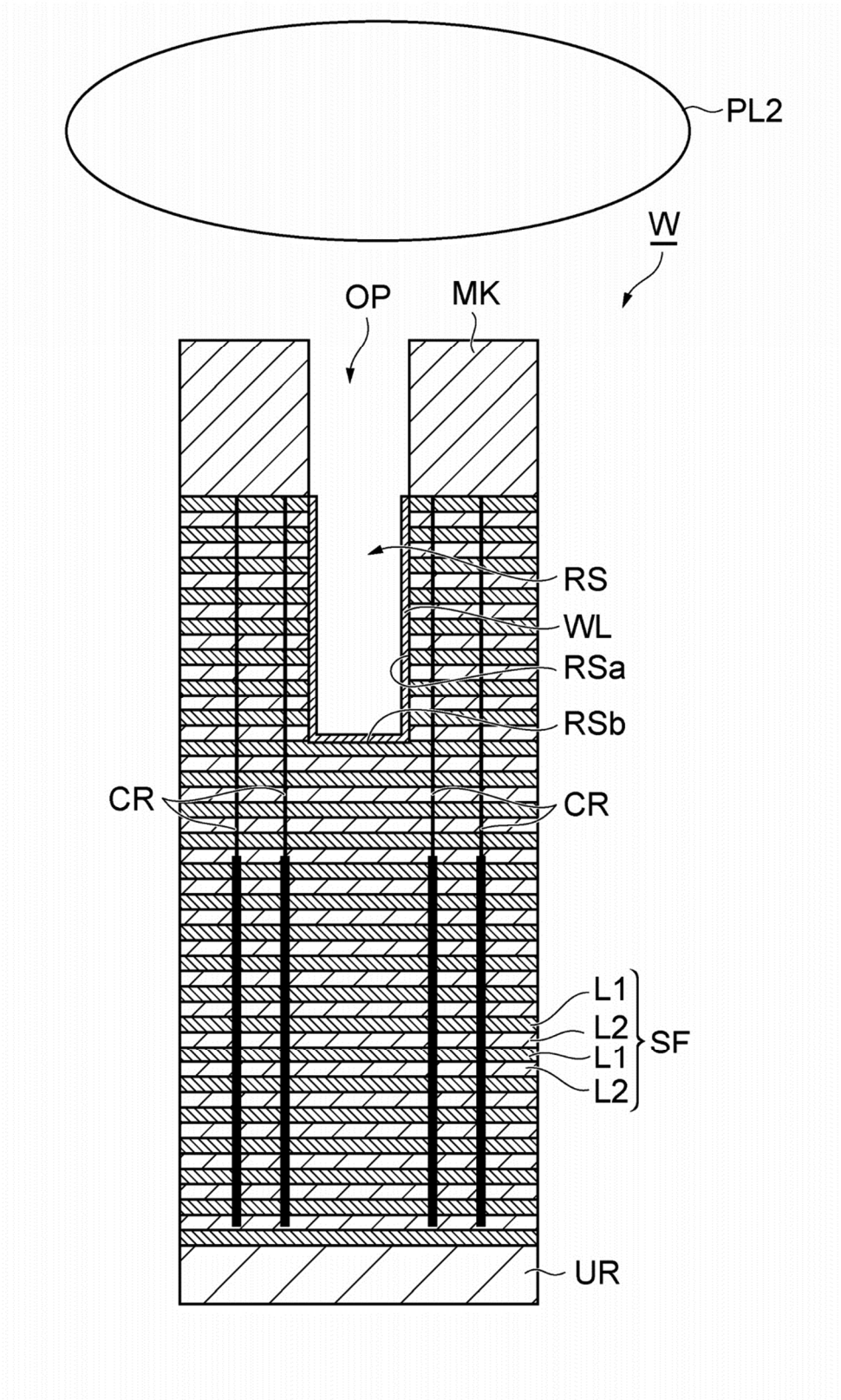


FIG. 7

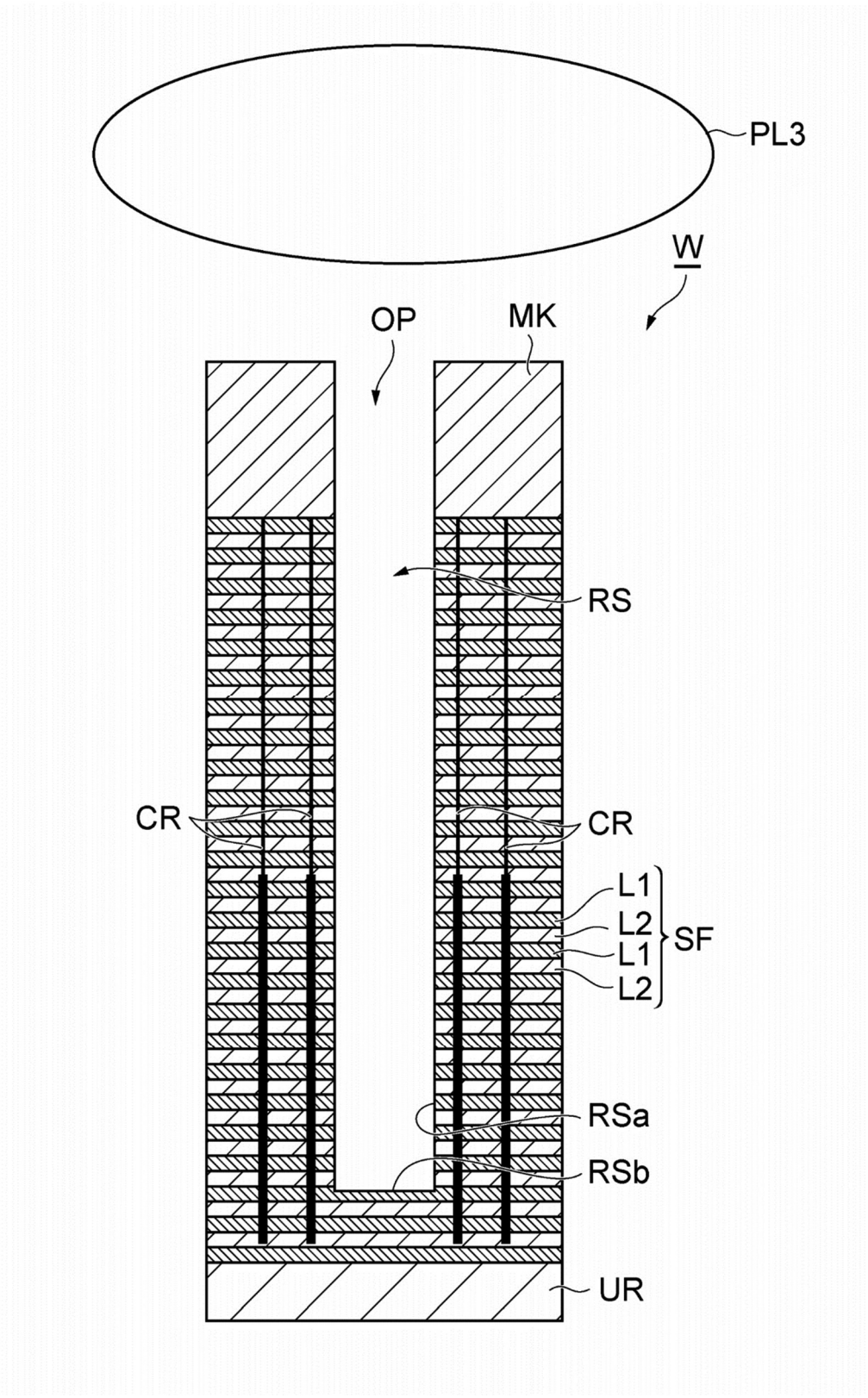


FIG. 8

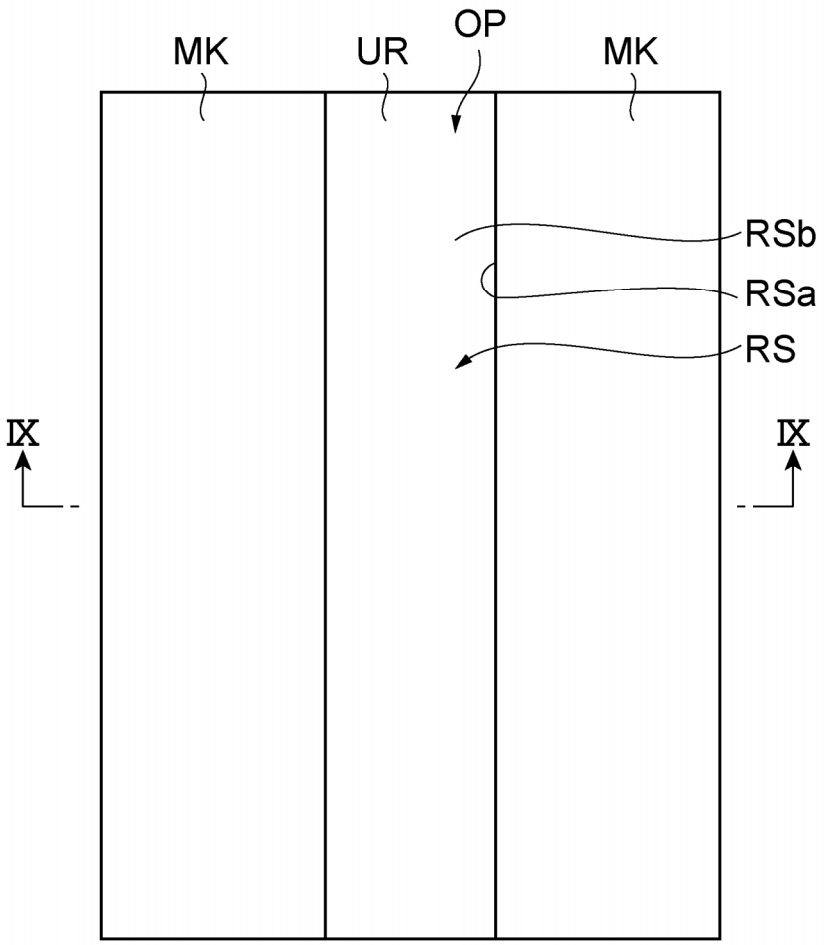


FIG. 9

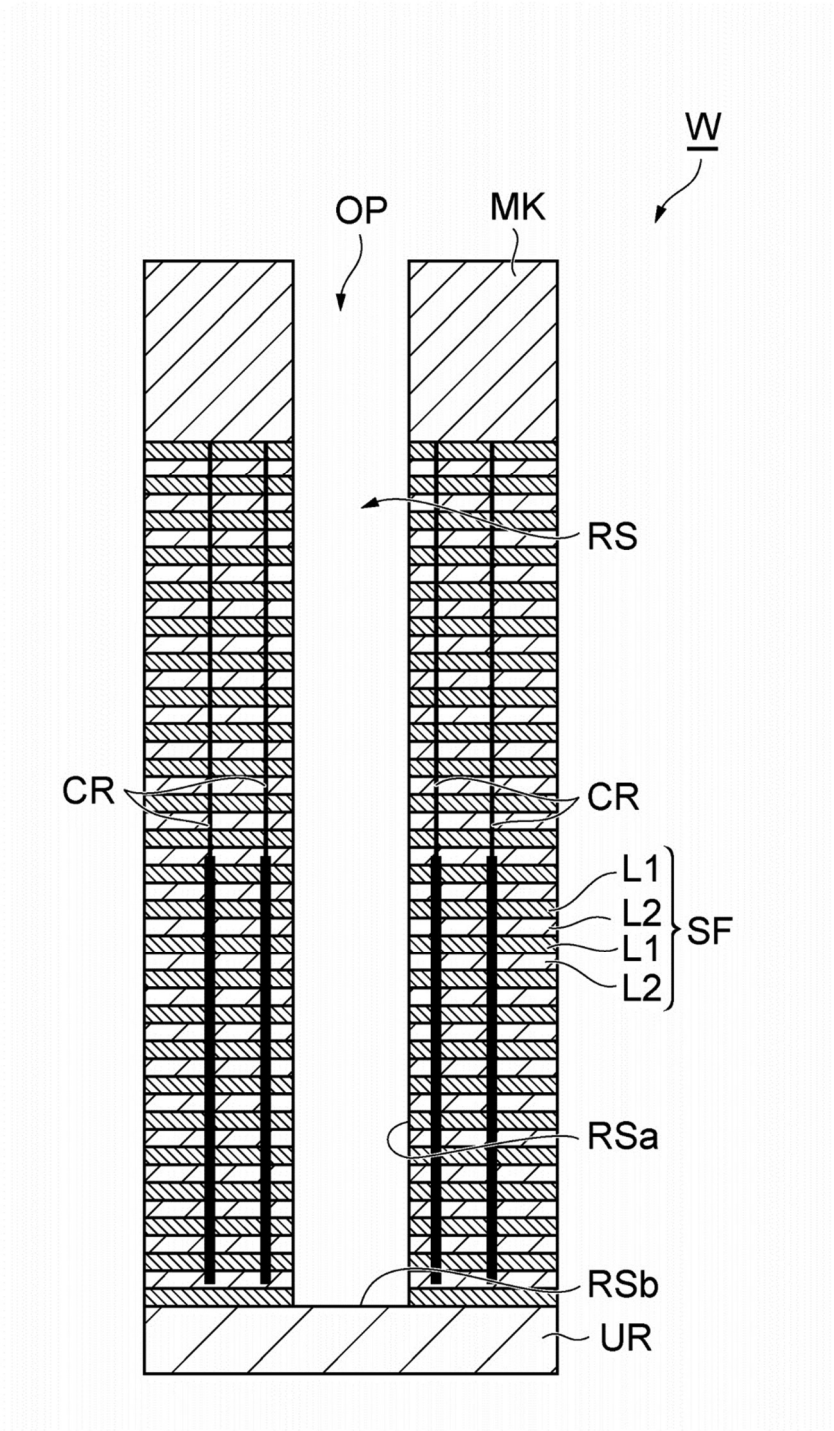


FIG. 10

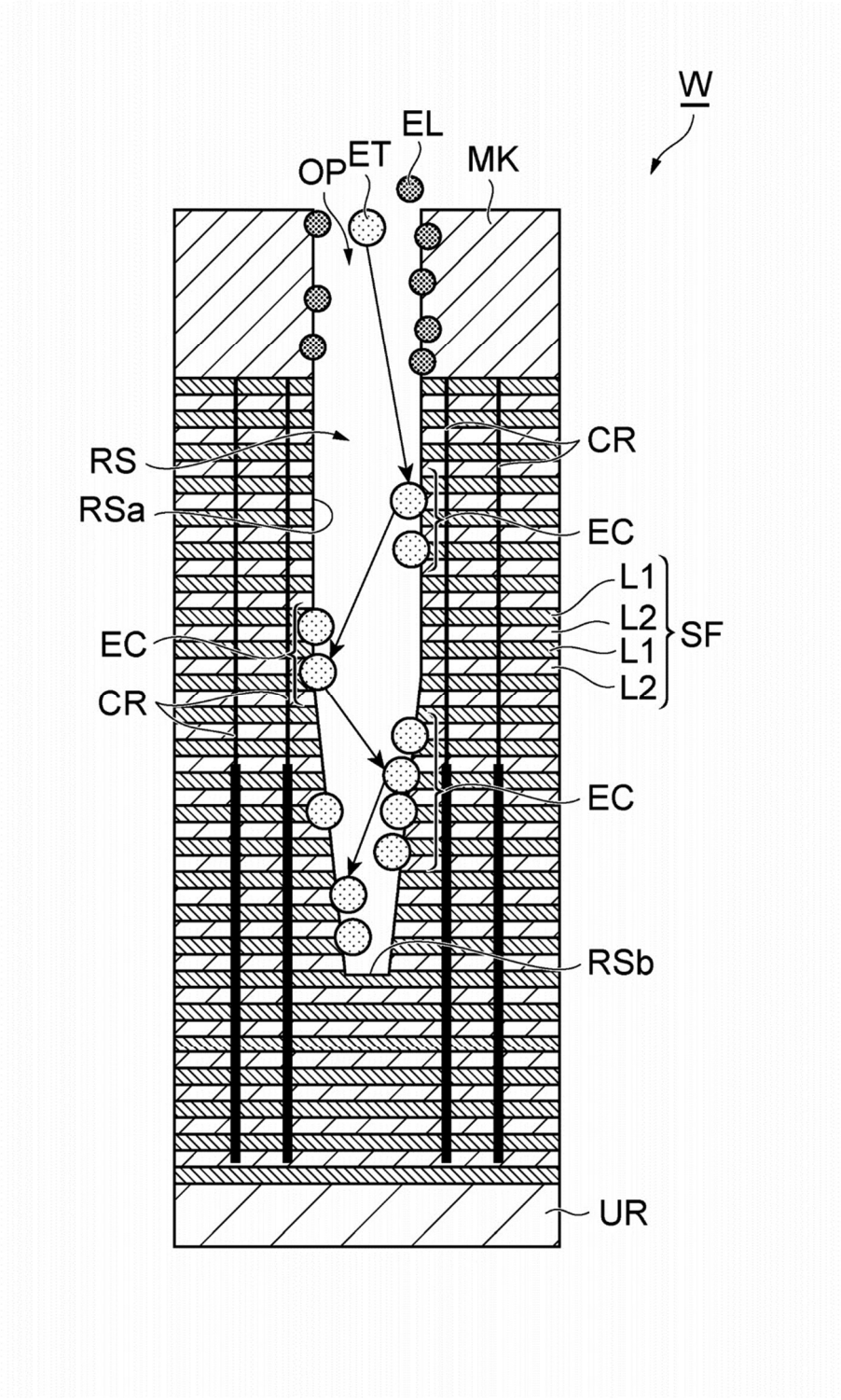


FIG. 11

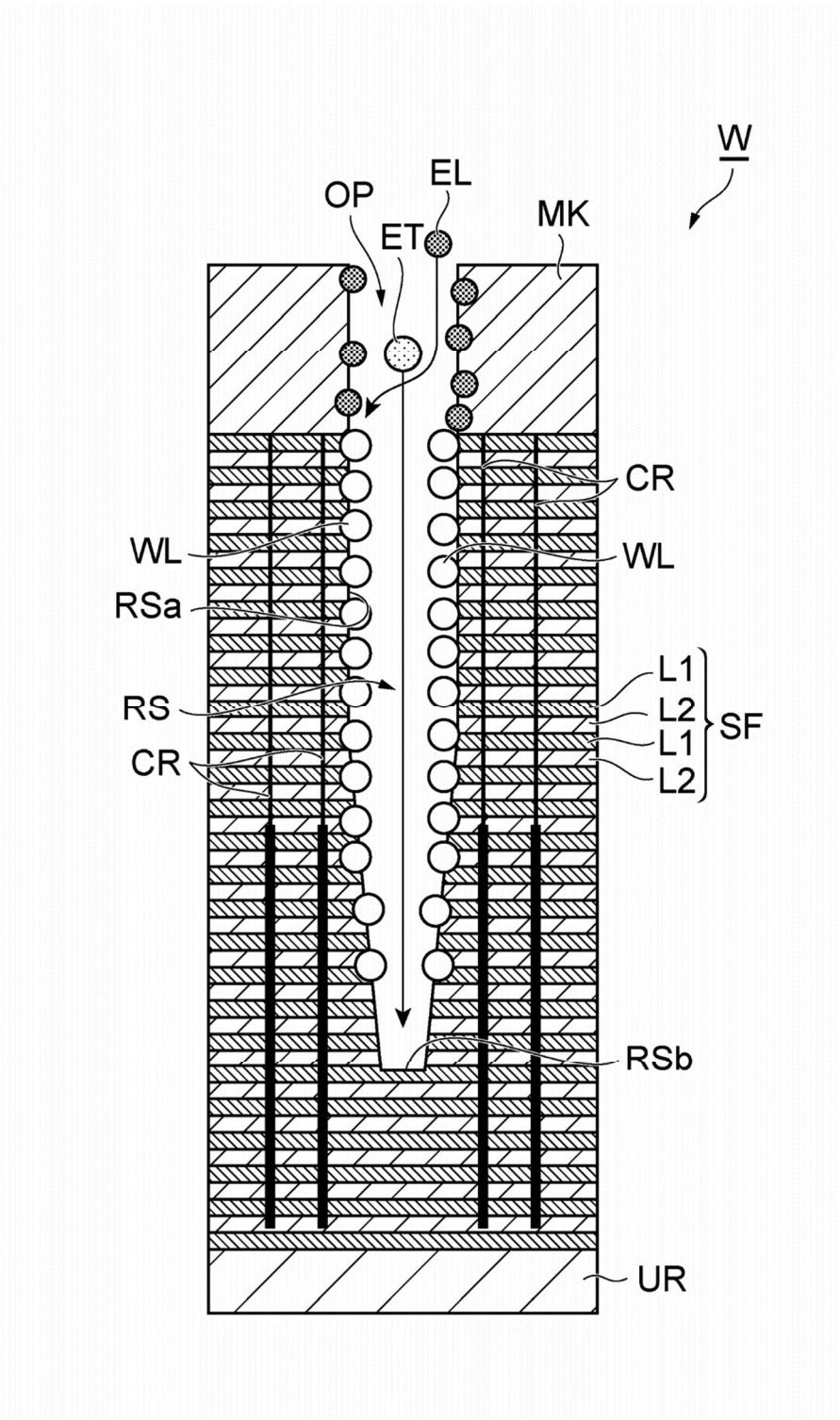


FIG. 12A

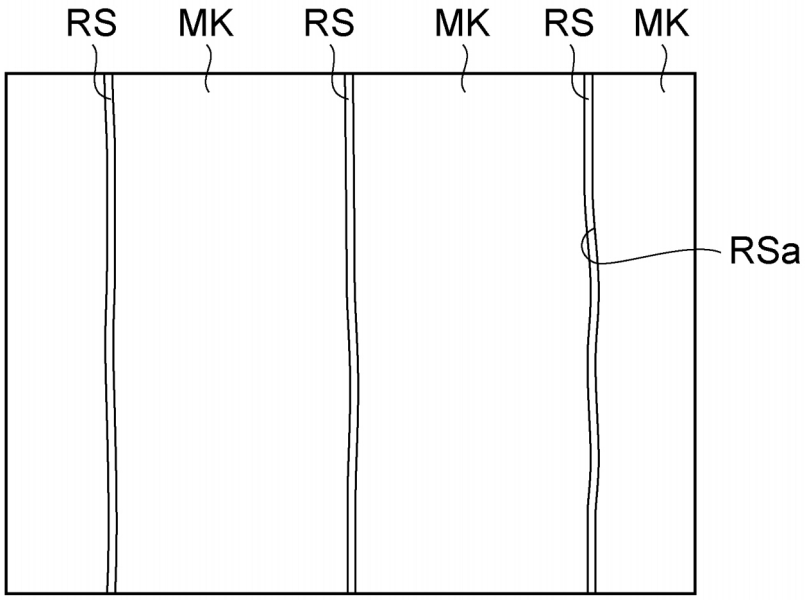
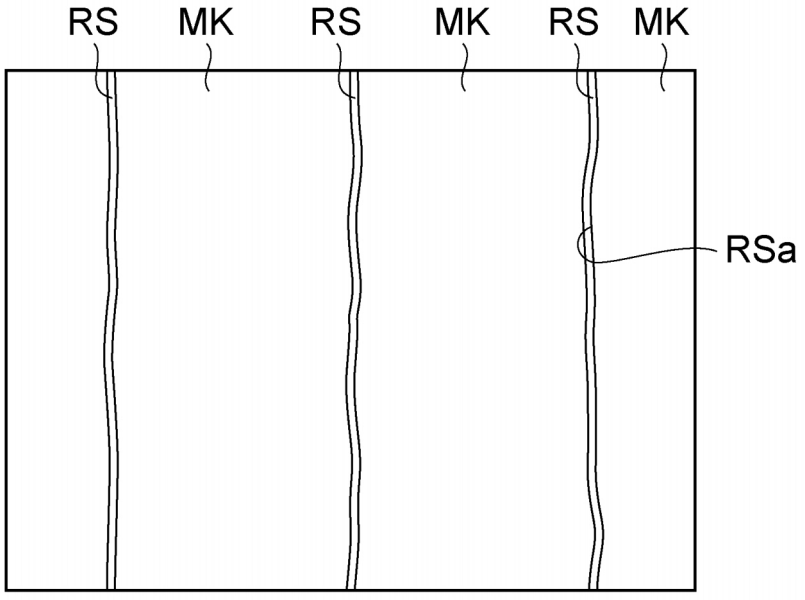


FIG. 12B



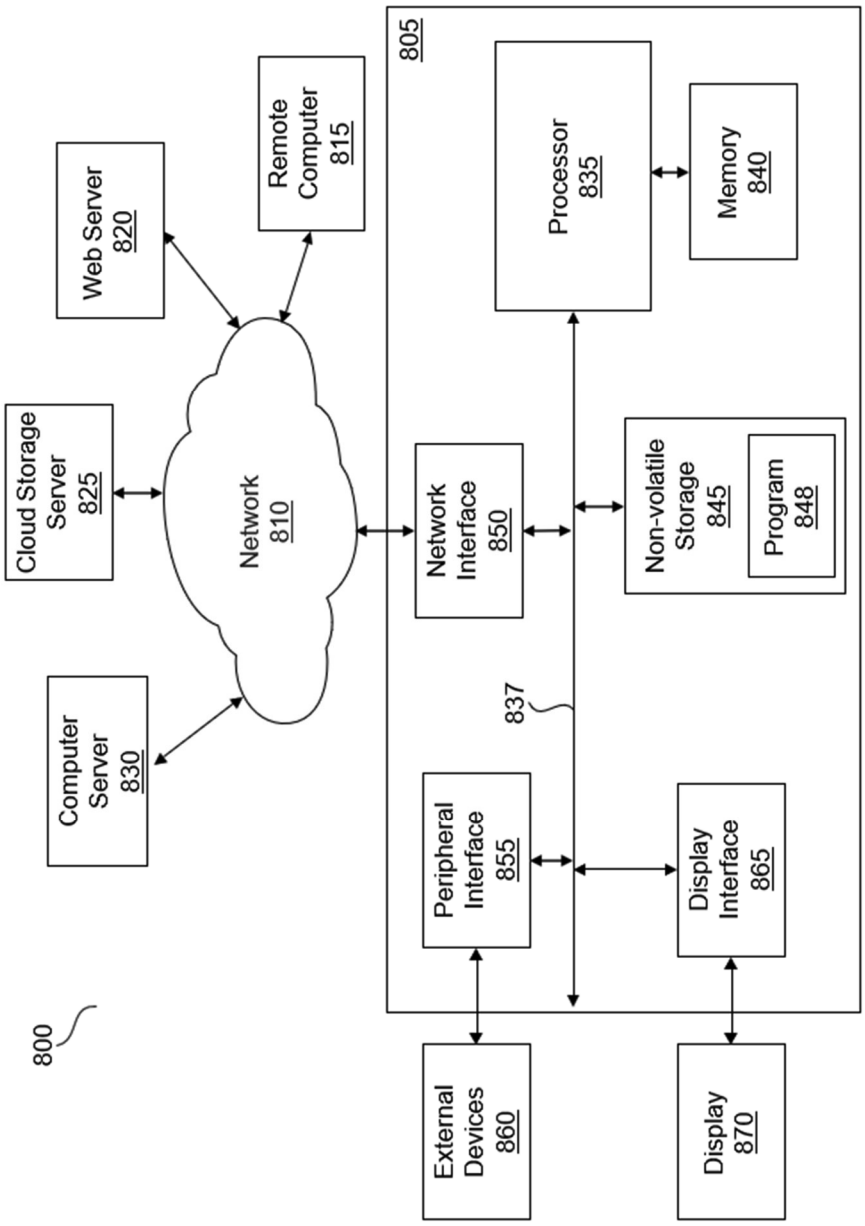

800
805
Remote Computer 815
Web Server 820
Cloud Storage Server 825
Computer Server 830
Network 810
Processor 835
Memory 840
Network Interface 850
Non-volatile Storage 845
Program 848
837
Peripheral Interface 855
Display Interface 865
External Devices 860
Display 870

FIG. 13